# Power Module Packaging Market: Global Industry Analysis, Trends, Market Size, and Forecasts up to 2032

Market Report | 2025-05-30 | 300 pages | Infinium Global Research and Consulting Solutions

**AVAILABLE LICENSES:**

- 1-5 User $4795.00
- Enterprise $7195.00

**Report description:**

The report on the global power module packaging market provides qualitative and quantitative analysis for the period from 2022-2032. The global power module packaging market was valued at USD 2351.28 million in 2023 and is expected to reach USD 4938.51 million in 2032, with a CAGR of 8.80% during the forecast period 2024-2032. The study on power module packaging market covers the analysis of the leading geographies such as North America, Europe, Asia Pacific, and RoW for the period of 2022-2032.
The report on power module packaging market is a comprehensive study and presentation of drivers, restraints, opportunities, demand factors, market size, forecasts, and trends in the global power module packaging market over the period of 2022-2032. Moreover, the report is a collective presentation of primary and secondary research findings.
Porter's five forces model in the report provides insights into the competitive rivalry, supplier and buyer positions in the market and opportunities for the new entrants in the global power module packaging market over the period of 2022-2032. Further, IGR-Growth Matrix gave in the report brings an insight into the investment areas that existing or new market players can consider.

Report Findings
1) Drivers
- The growing adoption of electric vehicles is fostering the power module packaging market.
- Increasing demand for high-efficiency power electronics is propelling the market growth.
2) Restraints
- High initial investment and manufacturing costs are hampering the growth of the market.
3) Opportunities
- Integration of AI in packaging design is expected to create lucrative opportunities in the market in the coming years.

Research Methodology
A) Primary Research
Our primary research involves extensive interviews and analysis of the opinions provided by the primary respondents. The

primary research starts with identifying and approaching the primary respondents, the primary respondents are approached include

1. Key Opinion Leaders associated with Infinium Global Research
2. Internal and External subject matter experts
3. Professionals and participants from the industry

Our primary research respondents typically include

1. Executives working with leading companies in the market under review
2. Product/brand/marketing managers
3. CXO level executives
4. Regional/zonal/ country managers
5. Vice President level executives.

B) Secondary Research

Secondary research involves extensive exploring through the secondary sources of information available in both the public domain and paid sources. At Infinium Global Research, each research study is based on over 500 hours of secondary research accompanied by primary research. The information obtained through the secondary sources is validated through the crosscheck on various data sources.

The secondary sources of the data typically include

1. Company reports and publications
2. Government/institutional publications
3. Trade and associations journals
4. Databases such as WTO, OECD, World Bank, and among others.
5. Websites and publications by research agencies

Segment Covered

The global power module packaging market is segmented on the basis of type, material, application, and end-use industry.

The Global Power Module Packaging Market by Type

- GaN module
- FET module
- SiC module
- IGBT module
- Thyristors

The Global Power Module Packaging Market by Material

- Substrate
- Die Attach
- Lead Frame Interconnection
- Substrate Attach
- Baseplate
- Encapsulations

The Global Power Module Packaging Market by Application

- Electric Vehicles (EVs)
- Wind Turbines
- Motors
- Rail Tractions
- Photovoltaic Equipment

The Global Power Module Packaging Market by End-use Industry
- IT
- Consumer
- Industrial
- Automatic

Company Profiles
The companies covered in the report include
- Mitsubishi Electric Corporation
- Fuji Electric Co., Ltd.
- Hitachi Energy Ltd.
- Infineon Technologies AG
- MacMic Science & Technology Co., Ltd.
- STMicroelectronics NV
- Texas Instruments Incorporated.
- StarPower Semiconductor Ltd.
- Semikron Danfoss
- SanRex Corporation

What does this Report Deliver?
1. Comprehensive analysis of the global as well as regional markets of the power module packaging market.
2. Complete coverage of all the segments in the power module packaging market to analyze the trends, developments in the global market and forecast of market size up to 2032.
3. Comprehensive analysis of the companies operating in the global power module packaging market. The company profile includes analysis of product portfolio, revenue, SWOT analysis and latest developments of the company.
4. IGR- Growth Matrix presents an analysis of the product segments and geographies that market players should focus to invest, consolidate, expand and/or diversify.

**Table of Contents:**

Table of Content

# Power Module Packaging Market: Global Industry Analysis, Trends, Market Size, and Forecasts up to 2032

Market Report | 2025-05-30 | 300 pages | Infinium Global Research and Consulting Solutions

To place an Order with Scotts International:

- - Print this form
- - Complete the relevant blank fields and sign
- - Send as a scanned email to support@scotts-international.com

**ORDER FORM:**

| Select license | License | Price |
|---|---|---|
| | 1-5 User | $4795.00 |
| | Enterprise | $7195.00 |
| | VAT | |
| | Total | |

*Please circle the relevant license option. For any questions please contact support@scotts-international.com or 0048 603 394 346.

** VAT will be added at 23% for Polish based companies, individuals and EU based companies who are unable to provide a valid EU Vat Numbers.

| | | | |
|---|---|---|---|
| Email* | | Phone* | |
| First Name* | | Last Name* | |
| Job title* | | | |
| Company Name* | | EU Vat / Tax ID / NIP number* | |
| Address* | | City* | |
| Zip Code* | | Country* | |
| | | Date | 2025-06-25 |
| | | Signature | |